1. **Manufacturer: Tokyo Electron Limited.**

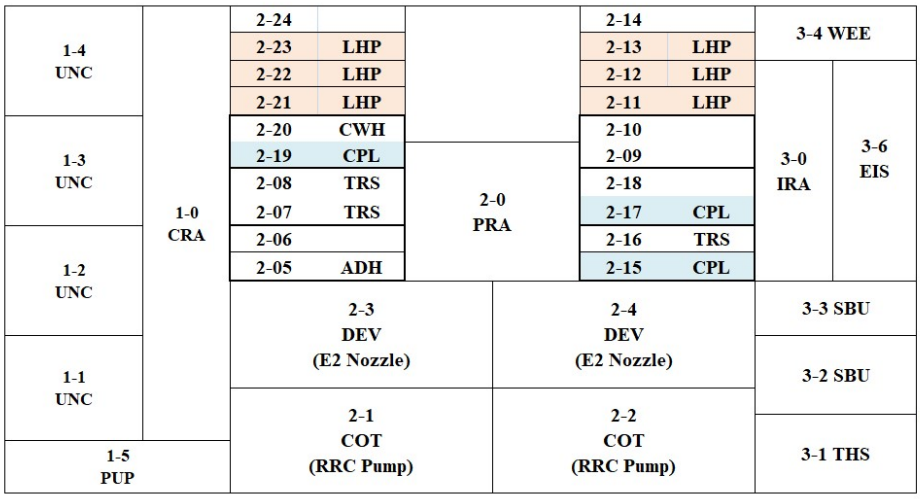
2. **Model:** TEL Clean Track ACT8

3. **Vintage**: September 2000

4. **Description:** Photo Resist Coat and Develop System

5. **Configuration**

1) **Block Diagram (Left to Right Wafer Flow)**



2) General Configuration

A. Wafer Size: 8inch Si Wafer

B. Wafer Flow: Left to Right

C. Process Block: 1ea (Single Block System)

D. Block #1

a. TEL Clean Track ACT 8 EC/Equipment Controller #2

b. Stage/Indexer: Open CSB/Cassette Stage Block

c. CRA/ Cassette Block Robotics Arm: 1ea

E. Block #2

a. Normal Coat Unit #2-1

- 3 Resist Dispense Nozzles
- Total 3 Resist Dispense Nozzles and 3 RRC Pumps
- 1 Solvent Pre-wet RRC/Reduced Resist Coat Nozzle
- 1 Side Rinse Nozzle (Programmable Side Rinse EBR)
- Dual Back Rinse Nozzles
- Photo Resist Temperature Control: Installed
- Motor Flange Temperature Control: Installed

- Photo Resist Drain Type: Direct Gravity Drain Type

b. Normal Coat Unit #2-2
- 3 Resist Dispense Nozzles
- Total 3Resist Dispense Nozzles and 3 RRC Pumps
- 1 Solvent Pre-wet RRC/Reduced Resist Coat Nozzle
- 1 Side Rinse Nozzle (Programmable Side Rinse EBR)
- Dual Back Rinse Nozzles
- Photo Resist Temperature Control: Installed
- Motor Flange Temperature Control: Installed
- Photo Resist Drain Type: Direct Gravity Drain Type

c. Develop Unit #2-3
- E2 Nozzle per Each Develop Unit
- 1 Top Rinse Nozzle per Each Develop Unit
- Dual Type Back Rinse Nozzles
- Develop Temperature Control: Installed
- Motor Flange Temperature Control: Installed
- Drain Type: Direct Gravity Drain Type
- Auto Damper: Installed
- Auto Dummy Dispense System: Installed

d. Develop Unit #2-4
- E2 Nozzle per Each Develop Unit
- 1 Top Rinse Nozzle per Each Develop Unit
- Dual Type Back Rinse Nozzles
- Develop Temperature Control: Installed
- Motor Flange Temperature Control: Installed
- Drain Type: Direct Gravity Drain Type
- Auto Damper: Installed
- Auto Dummy Dispense System: Installed

e. PRA/Process Block Robotics Arm: 1ea

f. ADH/Adhesion Process Station: 1ea

g. LHP/Low Temperature Hot Plate Station: 6ea

h. CPL/Chilling Pate Process Station: 3ea

i. TRS/Transition Stage Unit: 3ea

F. Block #3

a. IFB/Interface Block: 1ea (Standard Interface Block)

b. IRA/Interface Robotics Arm: 1ea

c. WEE/Wafer Edge Exposure Process Station: Installed

e. THS/Temporary Holding Stage: Installed

d. SBU/Stationary Buffer Unit: Installed

7. Chemical Supply System

A. Chemical Supply System/Cabinet #1

a. HMDS Supply System for 1ADH Unit

- 1/4Gal Bottle Supply System to Manul Supply with 1 Buffer Tanks

b. Develop Solution Supply System for 2 Develop Units

- Develop Solution Chemical Type: 1ea
- Tank Type:1 X 2 Buffer Tanks (3 Liter/Tank, Teflon) to cover 2 Develop Units

c. Solvent Supply System for 2 Coat Units

- Solvent Chemical Type: 1ea
- Tank Type: 1 x 2 Buffer Tanks (3 Liter/Tank, Teflon) to cover 2 Coat Units

8. Accessory Units

A. TEL OEM Power Transformer: 1ea

B. Temperature & Humidity Controller: Shinwa NRC 2-Cup

C. TEL OEM SMC TCU/Temperature Control Unit (Circulator Pumps, Thermo Controller) - 1ea